

# MOSFET – N-Channel, POWERTRENCH®

40 V, 49 A, 2.2 mΩ

## FDMS8460

### General Description

This N-Channel MOSFET is produced using onsemi's advanced POWERTRENCH® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- Max  $R_{DS(on)}$  = 2.2 mΩ at  $V_{GS} = 10\text{ V}$ ,  $I_D = 25\text{ A}$
- Max  $R_{DS(on)}$  = 3.0 mΩ at  $V_{GS} = 4.5\text{ V}$ ,  $I_D = 21.7\text{ A}$
- Advanced Package and Silicon Combination for Low  $R_{DS(on)}$
- MSL1 Robust Package Design
- 100% UIL Tested
- RoHS Compliant

### Applications

- DC-DC Conversion

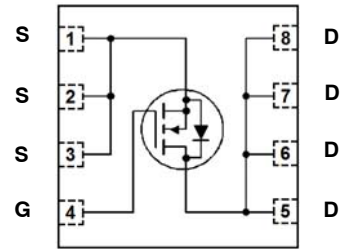
### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current:		A
	- Continuous (Package limited) $T_C = 25^\circ\text{C}$	49	
	- Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	167	
	- Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	25	
	- Pulsed	160	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	864	mJ
$P_D$	Power Dissipation:		W
	$T_C = 25^\circ\text{C}$ $T_A = 25^\circ\text{C}$ (Note 1a)	104 2.5	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

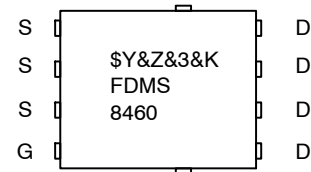
### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.2	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	



N-Channel MOSFET

### MARKING DIAGRAM



$\$Y$  = onsemi Logo  
 $\&Z$  = Assembly Plant Code  
 $\&3$  = Data Code (Year & Week)  
 $\&K$  = Lot  
 FDMS8460 = Specific Device Code

### ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

# FDMS8460

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V	40	–	–	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25°C	–	32	–	mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 32 V, V <sub>GS</sub> = 0 V	–	–	1	μA
I <sub>GSS</sub>	Gate to Source Leakage Current, Forward	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	–	–	±100	nA

### ON CHARACTERISTICS

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250 μA	1.0	1.9	3.0	V
ΔV <sub>GS(th)</sub> /ΔT <sub>J</sub>	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25°C	–	–7.5	–	mV/°C
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A	–	2.0	2.2	mΩ
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 21.7 A	–	2.6	3.0	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A, T <sub>J</sub> = 125°C	–	2.6	3.3	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 25 A	–	137	–	S

### DYNAMIC CHARACTERISTICS

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz	–	5415	7205	pF
C <sub>oss</sub>	Output Capacitance		–	1470	1955	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		–	170	250	pF
R <sub>g</sub>	Gate Resistance	f = 1MHz	0.1	1.4	3.1	Ω

### SWITCHING CHARACTERISTICS

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 25 A, V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 6 Ω	–	19	35	ns
t <sub>r</sub>	Rise Time		–	9	19	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		–	48	78	ns
t <sub>f</sub>	Fall Time		–	7	14	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V, V <sub>DD</sub> = 20 V, I <sub>D</sub> = 25 A	–	78	110	nC
		V <sub>GS</sub> = 0 V to 4.5 V, V <sub>DD</sub> = 20 V, I <sub>D</sub> = 25 A	–	36	51	nC
Q <sub>gs</sub>	Gate to Source Charge	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 25 A	–	15	–	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		–	10	–	nC

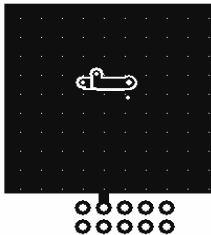
### DRAIN-SOURCE DIODE CHARACTERISTICS

V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 25 A (Note 2)	–	0.8	1.3	V
		V <sub>GS</sub> = 0 V, I <sub>S</sub> = 2.1 A (Note 2)	–	0.7	1.2	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 25 A, di/dt = 100 A/μs	–	53	85	ns
Q <sub>rr</sub>	Reverse Recovery Charge		–	40	64	nC

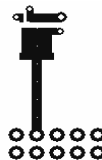
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. R<sub>θJA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 × 1.5 in. board of FR-4 material. R<sub>θCA</sub> is determined by the user's board design.

#### NOTES:



a. 50 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.
3. Starting T<sub>J</sub> = 25°C, L = 0.3 mH, I<sub>AS</sub> = 24 A, V<sub>DD</sub> = 40 V, V<sub>GS</sub> = 10 V

TYPICAL CHARACTERISTICS

( $T_J = 25^\circ\text{C}$  unless otherwise noted)

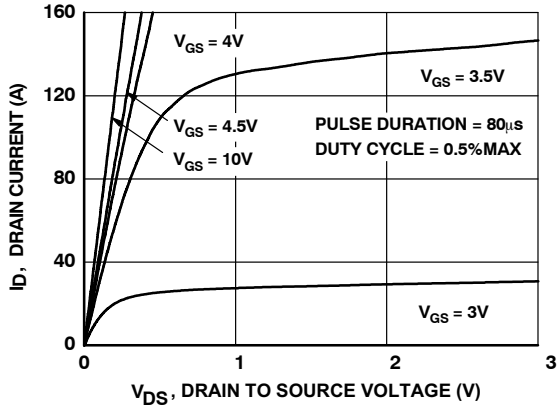


Figure 1. On Region Characteristics

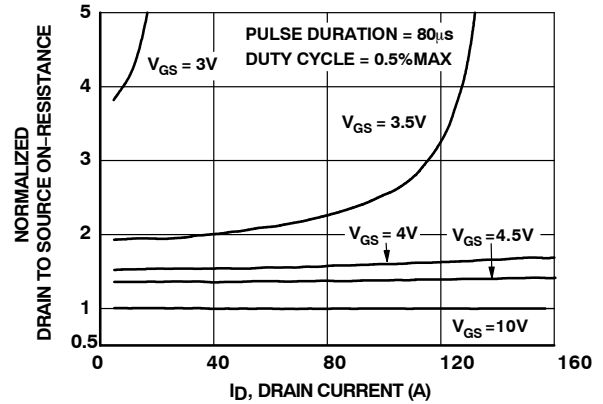


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

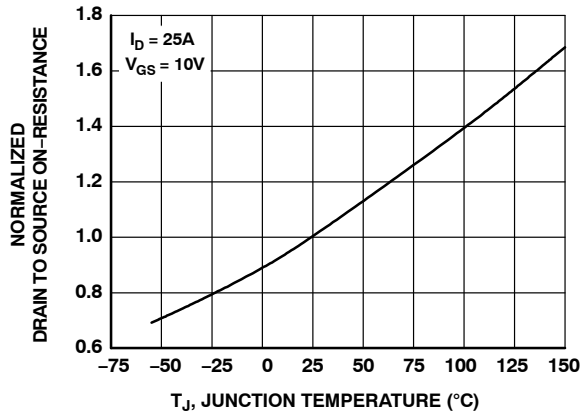


Figure 3. Normalized On Resistance vs. Junction Temperature

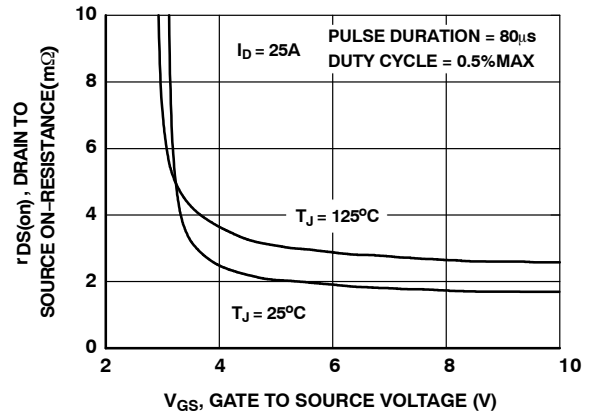


Figure 4. On-Resistance vs. Gate to Source Voltage

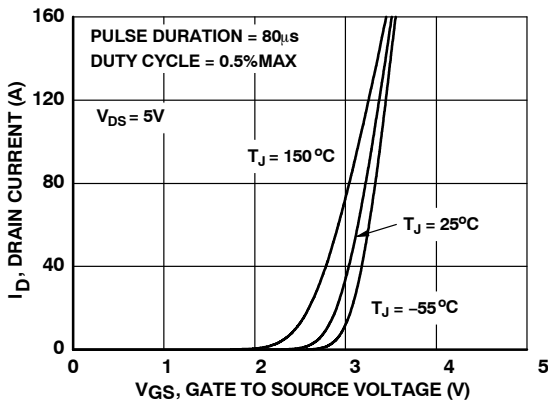


Figure 5. Transfer Characteristics

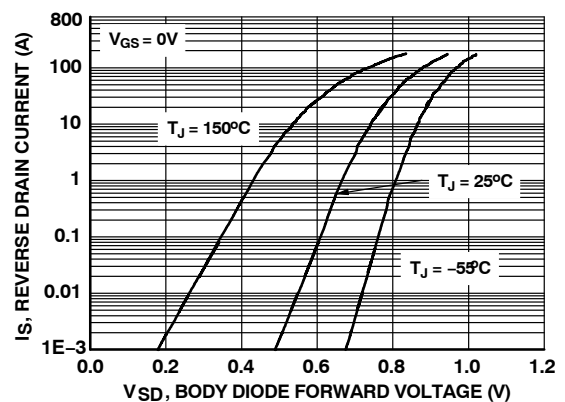


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS (continued)

( $T_J = 25^\circ\text{C}$  unless otherwise noted)

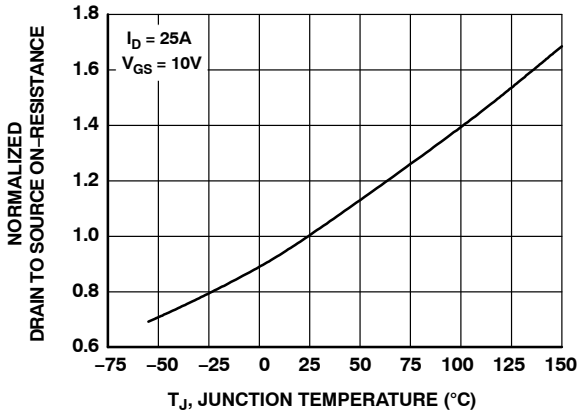


Figure 7. Normalized On Resistance vs. Junction Temperature

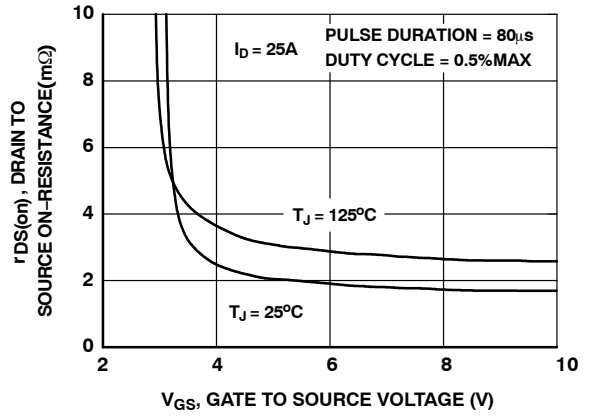


Figure 8. On-Resistance vs. Gate to Source Voltage

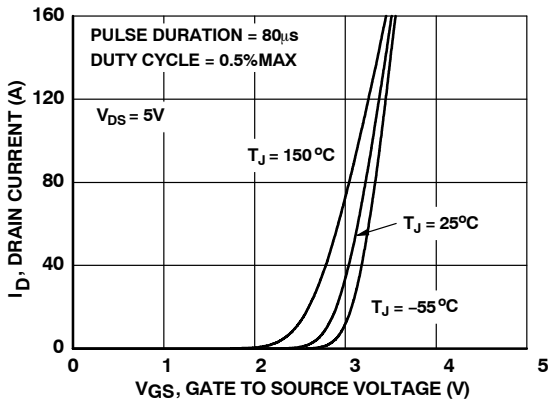


Figure 9. Transfer Characteristics

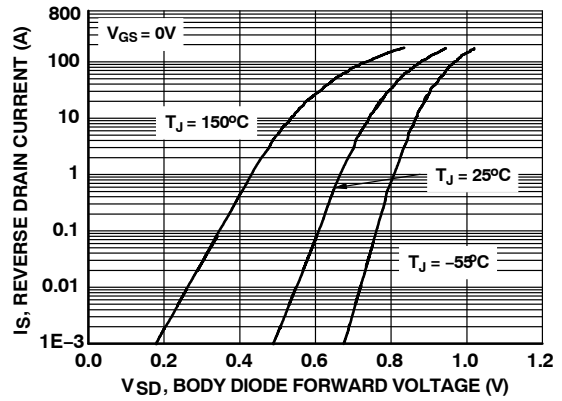


Figure 10. Source to Drain Diode Forward Voltage vs. Source Current

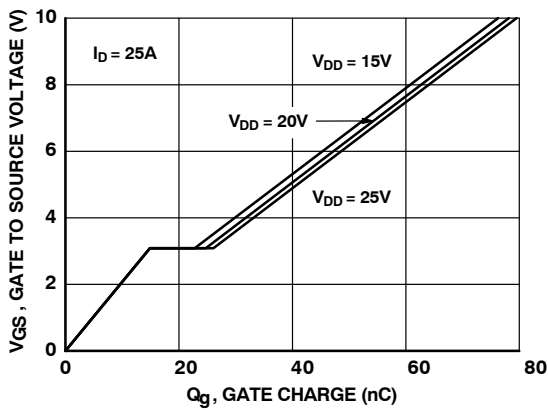


Figure 11. Gate Charge Characteristics

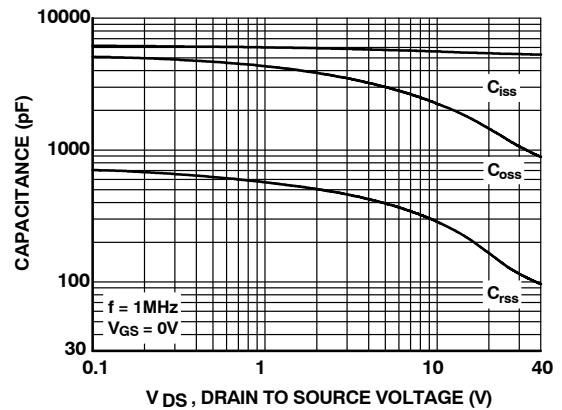


Figure 12. Capacitance vs. Drain to Source Voltage

TYPICAL CHARACTERISTICS (continued)

( $T_J = 25^\circ\text{C}$  unless otherwise noted)

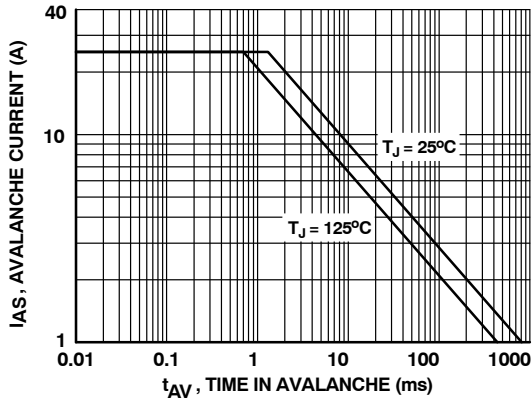


Figure 13. Unclamped Inductive Switching Capability

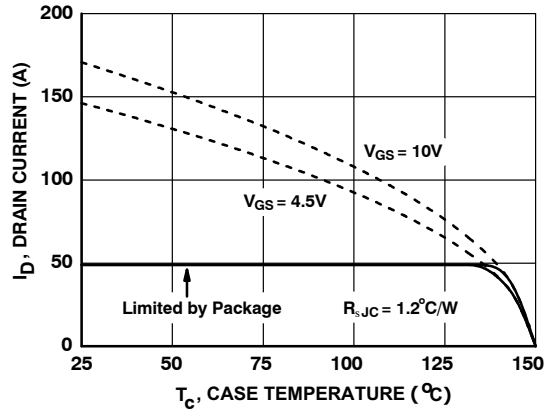


Figure 14. Maximum Continuous Drain Current vs. Case Temperature

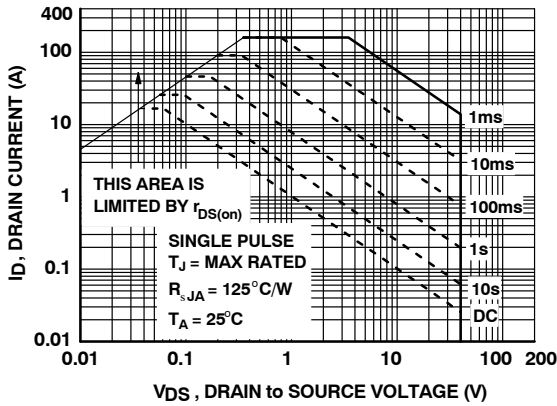


Figure 15. Forward Bias Safe Operating Area

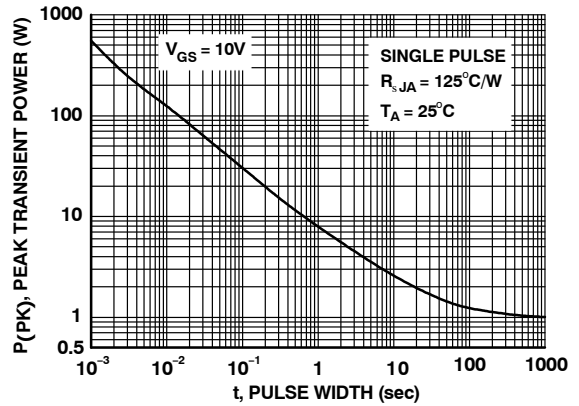


Figure 16. Single Pulse Maximum Power Dissipation

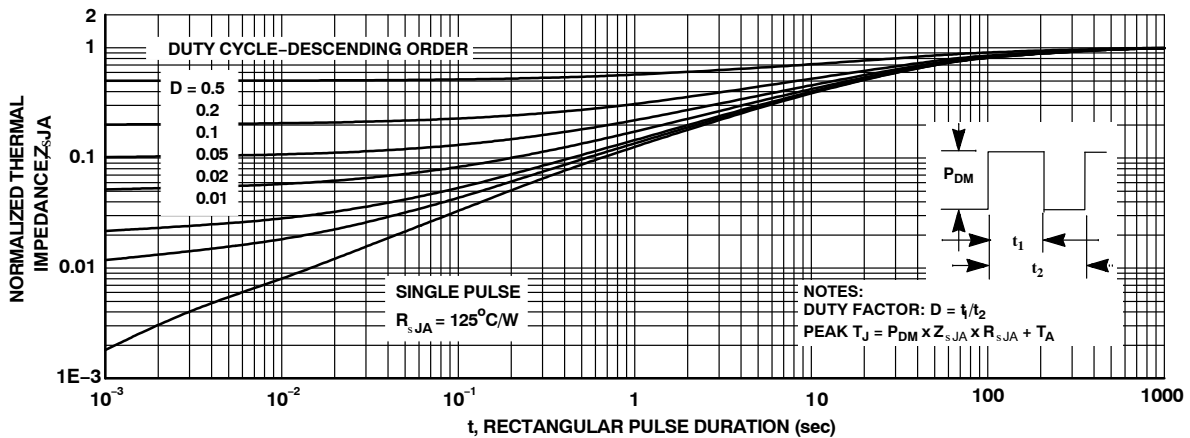


Figure 17. Transient Thermal Response Curve

# FDMS8460

## PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Shipping <sup>†</sup>
FDMS8460	FDMS8460	Power 56 (PQFN8) (Pb-Free / Halogen Free)	3,000/Tape&Reel

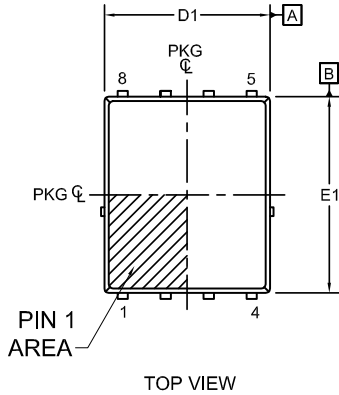
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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**PQFN8 5X6, 1.27P**  
**CASE 483AE**  
**ISSUE C**

DATE 21 JAN 2022

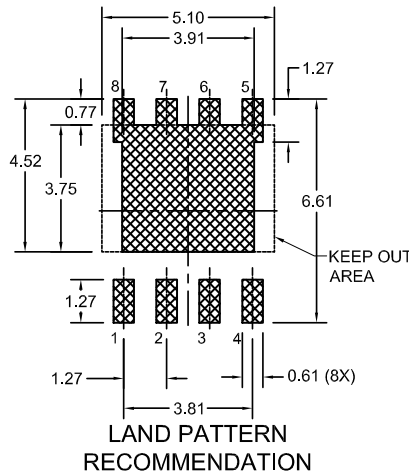
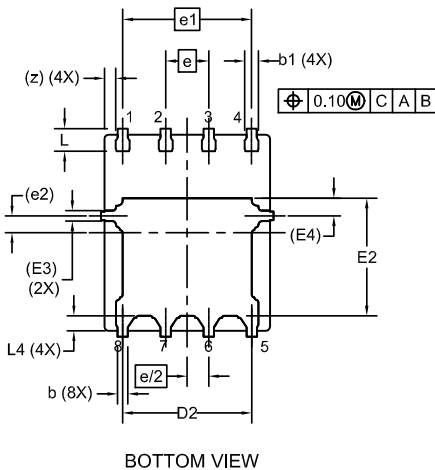


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.21	0.31	0.41
b1	0.31	0.41	0.51
A3	0.15	0.25	0.35
D	4.90	5.00	5.20
D1	4.80	4.90	5.00
D2	3.61	3.82	3.96
E	5.90	6.15	6.25
E1	5.70	5.80	5.90
E2	3.38	3.48	3.78
E3	0.30 REF		
E4	0.52 REF		
e	1.27 BSC		
e/2	0.635 BSC		
e1	3.81 BSC		
e2	0.50 REF		
L	0.51	0.66	0.76
L2	0.05	0.18	0.30
L4	0.34	0.44	0.54
z	0.34 REF		
θ	0°	-	12°



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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